

Features

- Lead free
- RoHS compliant*
- Bifilar or sector windings
- Wide frequency range over 1000MHz
- Rated current 0.2 to 0.5A
- Model DR331 recommended for new designs

Applications

- For the suppression of EMI in data and signal lines, e.g. CAN Bus

DR332 Series Surface Mount Data Line Chokes

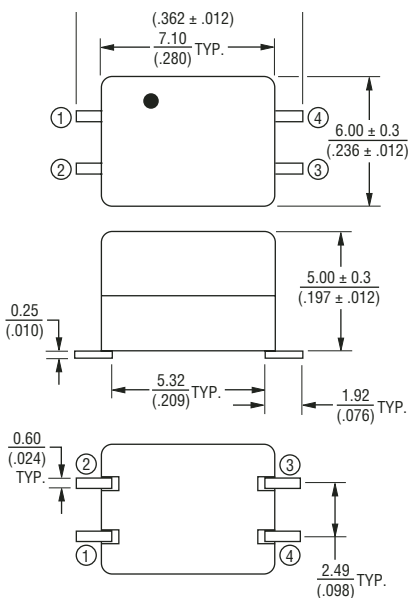
Electrical Characteristics (@ 25 °C)

Bourns Part Number	L (1-4) @ 100 kHz, 0.1 Vrms (μH)	LL (1-4) @ 100 kHz, 0.1 Vrms (Typ.) (2-3 Short)	RDC (Ω) (Winding) Max. (Ω)	Rated Current Max.	Winding
DR332-113AE	11.0 +25 %	0.05 μH	0.12	0.5 A	Bifilar
DR332-253AE	25.0 +25 %	1.50 μH	0.20	0.5 A	Sector
DR332-513AE	51.0 +25 %	2.00 μH	0.30	0.5 A	Sector
DR332-474AE	470.0 +25 %	0.28 μH	0.28	0.5 A	Bifilar
DR332-105AE	1000.0 +25 %	0.29 μH	0.40	0.5 A	Bifilar
DR332-475AE	4700.0 +25 %	0.30 μH	0.70	0.2 A	Bifilar

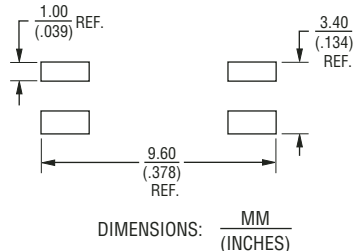
Note: For tape and reel packaging, add "E" at the end of part number.

Rated Voltage80 Vdc/42 Vac
 Hipot (1 sec.).....250 Vac/60 Hz, 3 mA
 *Operating Temperature ..-40 to +135 °C
 *Storage Temperature-40 to +135 °C
 Temperature Rise
30 °C max. at rated current
 Resistance to Solder Heat
260 °C 10 sec.
 CoreFerrite
 WireEnameled copper wire (Class F)
 BasePPHS (UL 94V-0)
 TerminalCu/Ni/Sn
 Adhesive.....Epoxy resin
 Packaging1500 pcs. per reel

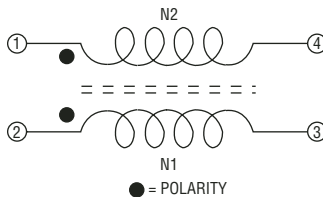
Product Dimensions



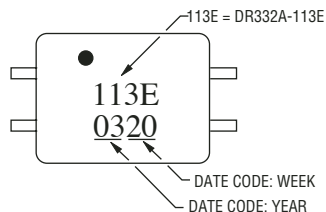
Recommended PCB Layout



Schematic



Typical Part Marking



*Model DR443-475:
 Operating Temperature-40 to +100 °C
 Storage Temperature-40 to +100 °C

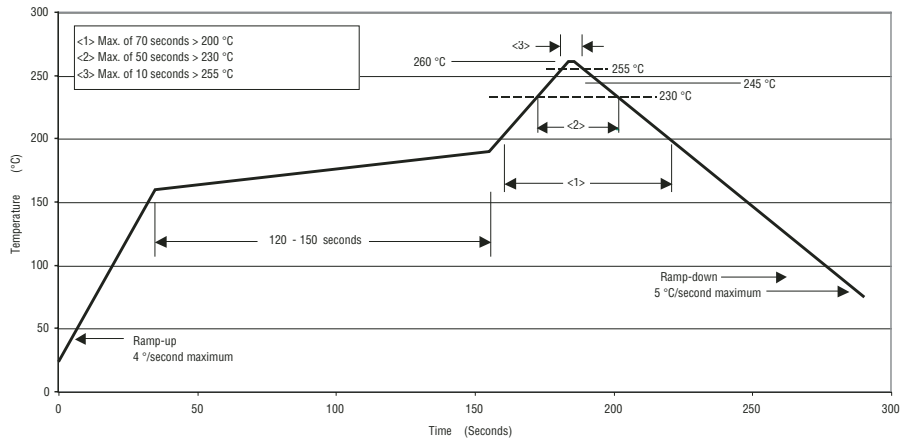
How to Order

Model DR332 - 513 AE
 Value Code _____
 See Model-Value Table
 Termination _____
 AE = Cu/Ni/Sn (Lead Free)

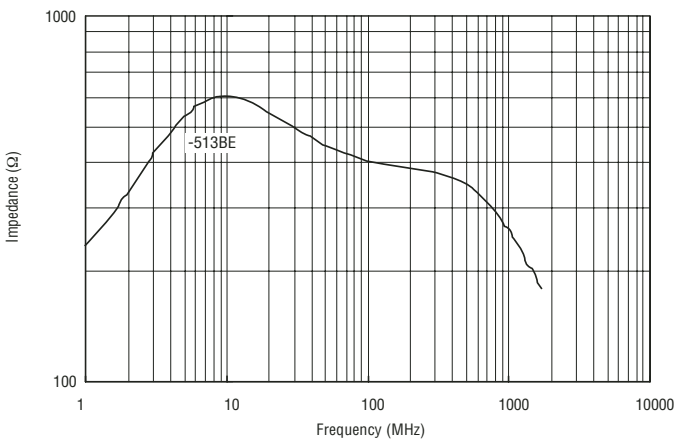
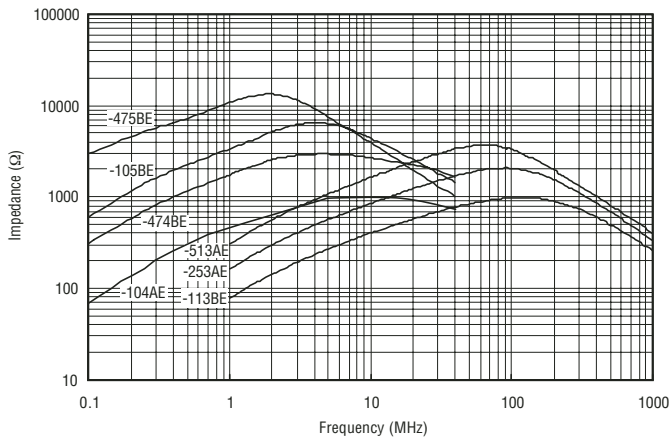
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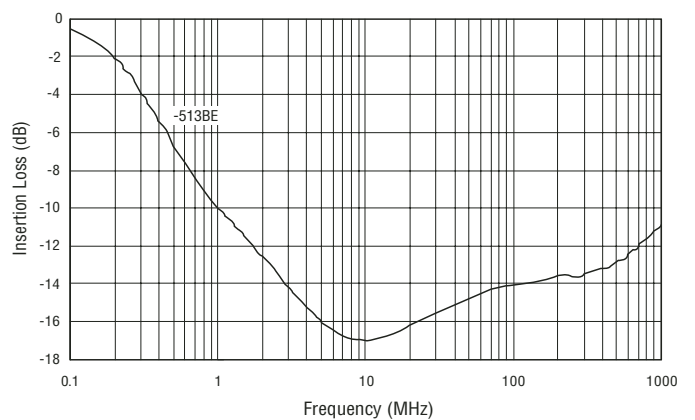
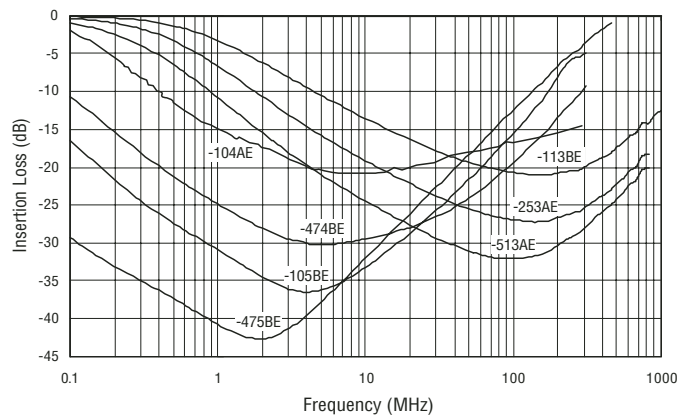
Solder Profile



Impedance vs. Frequency



Insertion Loss vs. Frequency



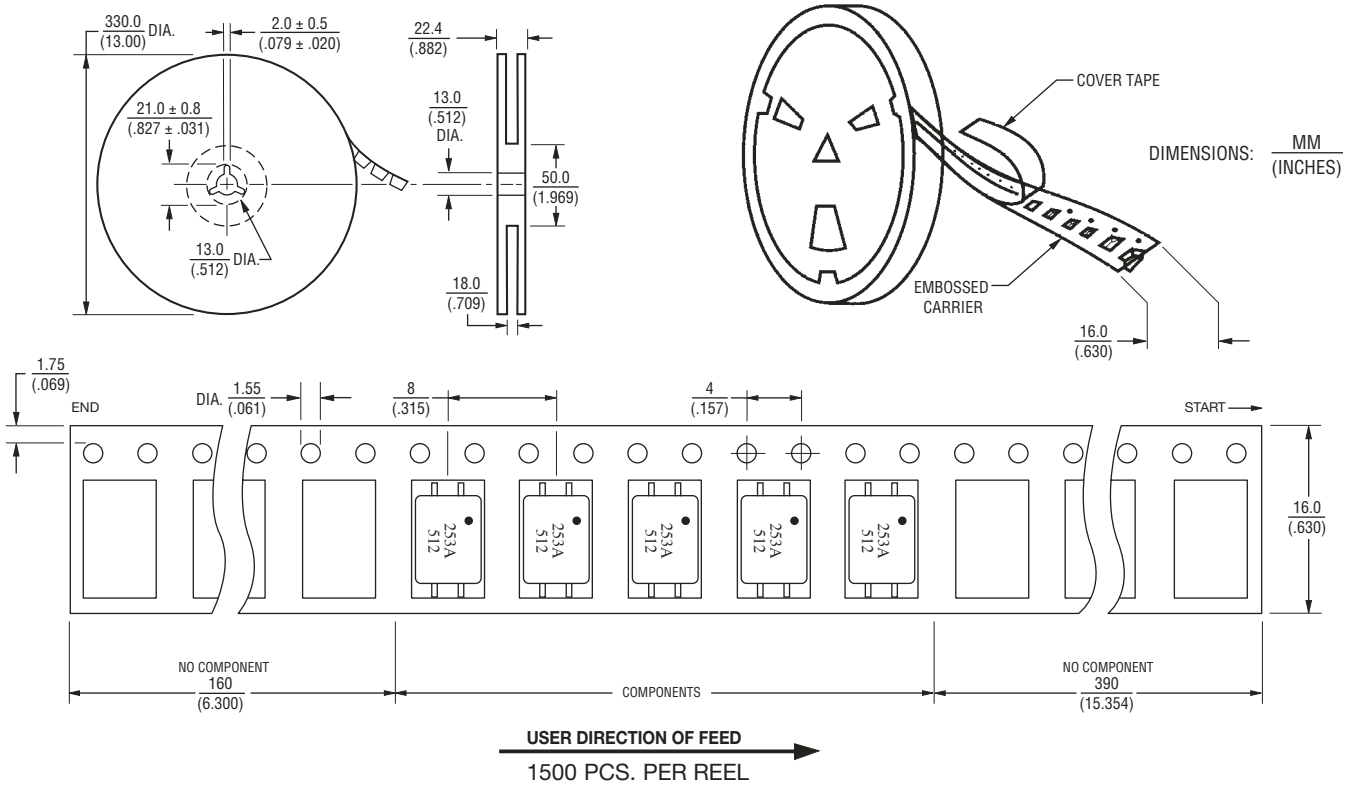
REV. 05/05

Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.

DR332 Series Surface Mount Data Line Chokes

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Packaging Specifications



REV. 05/05

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